## DISCRETE SEMICONDUCTORS

# DATA SHEET

**PEMD13**; **PUMD13** NPN/PNP resistor-equipped transistors; R1 = 4.7 kΩ, R2 = 47 kΩ

Product specification Supersedes data of 2001 Feb 27 2003 Oct 08





# NPN/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

PEMD13; PUMD13

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

#### **APPLICATIONS**

- · Low current peripheral driver
- Replacement of general purpose transistors in digital applications
- · Control of IC inputs.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	50	V
I <sub>O</sub>	output current (DC)	_	100	mA
TR1	NPN	_	_	ı
TR2	PNP	_	_	1
R1	bias resistor	4.7	-	kΩ
R2	bias resistor	47	_	kΩ

#### **DESCRIPTION**

NPN/PNP resistor-equipped transistors (see "Simplified outline, symbol and pinning" for package details).

#### PRODUCT OVERVIEW

TYPE	PAC	KAGE	MARKING CODE	PNP/PNP	NPN/NPN
NUMBER	PHILIPS	EIAJ	WARKING CODE	COMPLEMENT	COMPLEMENT
PEMD13	SOT666		Z1	PEMB13	PEMH13
PUMD13	SOT363	SC-88	3*1 <sup>(1)</sup>	PUMB13	PUMH13

### Note

- \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
  - \* = W: Made in China.

### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL		PINNING
I TPE NUMBER	SIMPLIFIED OUTLINE AND STMBOL	PIN	DESCRIPTION
PEMD13	6 5 4	1	emitter TR1
PUMD13		2	base TR1
	R1 R2	3	collector TR2
	TR2	4	emitter TR2
		5	base TR2
	│	6	collector TR1
	1 2 3		
	1 2 3 Top view 1 2 3		

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## **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE	
I TPE NUMBER	NAME	DESCRIPTION	VERSION
PEMD13	_	plastic surface mounted package; 6 leads	SOT666
PUMD13	_	plastic surface mounted package; 6 leads	SOT363

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT					
Per transist	Per transistor; for the PNP transistor with negative polarity									
V <sub>CBO</sub>	collector-base voltage	open emitter	_	50	V					
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V					
V <sub>EBO</sub>	emitter-base voltage	open collector	_	10	V					
VI	input voltage TR1									
	positive		_	+30	V					
	negative		_	-5	V					
V <sub>I</sub>	input voltage TR2									
	positive		_	+5	V					
	negative		_	-30	V					
Io	output current (DC)		_	100	mA					
I <sub>CM</sub>	peak collector current		_	100	mA					
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C								
	SOT363	note 1	_	200	mW					
	SOT666	notes 1 and 2	_	200	mW					
T <sub>stg</sub>	storage temperature		-65	+150	°C					
Tj	junction temperature		_	150	°C					
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C					
Per device				•	•					
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C								
	SOT363	note 1	_	300	mW					
	SOT666	notes 1 and 2	_	300	mW					

#### **Notes**

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.
- 2. Reflow soldering is the only recommended soldering method.

# NPN/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

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### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Per transist	or			
R <sub>th j-a</sub>	thermal resistance from junction to ambient	T <sub>amb</sub> ≤ 25 °C		
	SOT363	note 1	625	K/W
	SOT666	notes 1 and 2	625	K/W
Per device				
R <sub>th j-a</sub>	thermal resistance from junction to ambient	T <sub>amb</sub> ≤ 25 °C		
	SOT363	note 1	416	K/W
	SOT666	notes 1 and 2	416	K/W

#### **Notes**

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.
- 2. Reflow soldering is the only recommended soldering method.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT			
Per transistor; for the PNP transistor with negative polarity									
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0	_	_	100	nA			
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0	_	_	1	μΑ			
		V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0; T <sub>j</sub> = 150 °C	_	_	50	μΑ			
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0	_	_	170	μΑ			
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 10 mA	100	_	_				
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 5 \text{ mA}; I_B = 0.25 \text{ mA}$	_	_	100	mV			
V <sub>i(off)</sub>	input-off voltage	I <sub>C</sub> = 100 μA; V <sub>CE</sub> = 5 V	_	0.6	0.5	V			
V <sub>i(on)</sub>	input-on voltage	$I_C = 5 \text{ mA}; V_{CE} = 0.3 \text{ V}$	1.3	0.9	_	V			
R1	input resistor		3.3	4.7	6.1	kΩ			
R2 R1	resistor ratio		8	10	12				
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 10 \text{ V}$ ; $f = 1 \text{ MHz}$							
	TR1 (NPN)		_	_	2.5	pF			
	TR2 (PNP)		_	_	3	pF			

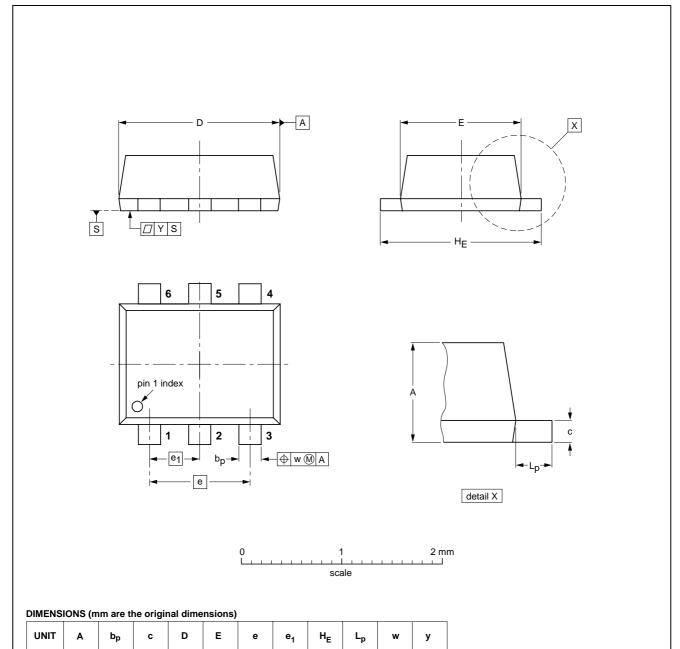
# NPN/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

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### **PACKAGE OUTLINES**

Plastic surface mounted package; 6 leads

SOT666



OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT666						<del>-01-01-04</del> 01-08-27

0.1

1.0

0.5

2003 Oct 08 5

0.6

mm

0.27

0.17

0.18

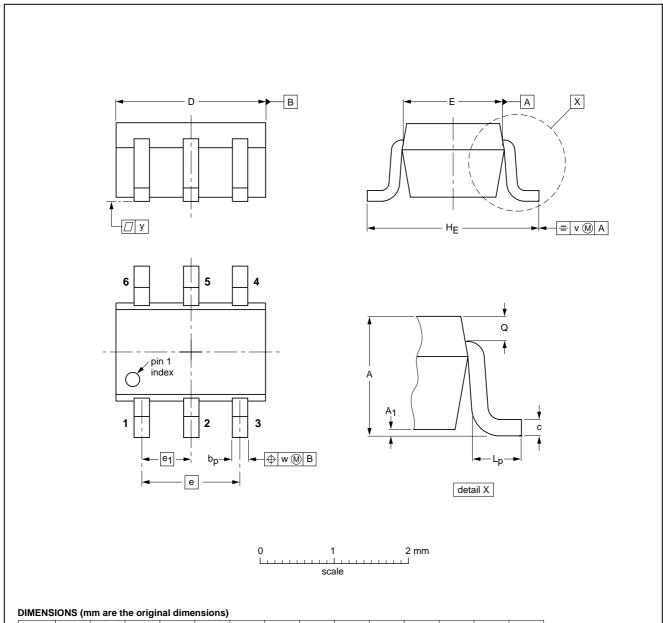
0.08

# NPN/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

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### Plastic surface mounted package; 6 leads

**SOT363** 



UNIT	Α	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w	у	
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1	

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT363			SC-88			97-02-28

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#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### **DEFINITIONS**

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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